

Proposed New Claims:

1. A semiconductor package comprising:

a semiconductor wafer with at least one semiconductor die created therein,

a plurality of bond pads formed on a surface of the semiconductor wafer,

a glass sheet having holes formed therein, wherein the size of the glass sheet matches the size of the semiconductor wafer,

a first layer of conductive material deposited on the surface of the glass sheet, wherein the conductive material is deposited to create conductive traces on the glass sheet that are connected to the holes in the glass sheet,

a layer of adhesive material disposed on the surface of the semiconductor wafer, wherein the layer of adhesive affixes the glass sheet to the semiconductor wafer such that the holes in the glass sheet are aligned with the location of the bond pads on the semiconductor wafer,

a second layer of conductive material deposited on the surface of the glass sheet, wherein the conductive material extends through the holes in the glass sheet to electrically connect the conductive traces on the glass sheet to the bond pads on the surface of the semiconductor wafer, and

a plurality of solder balls disposed on the conductive traces such that an electrical connection is made between each solder ball and a corresponding bond pad on the surface of the semiconductor wafer.

2. The semiconductor package of Claim 1, and wherein the semiconductor wafer contains a plurality of semiconductor die and the semiconductor wafer is disposed to be divided into a plurality of individual packaged semiconductor die.